

Power Supply Input

Var	Value	Units	Description
VACMIN	85	V	Minimum Input AC Voltage
VACMAX	265	V	Maximum Input AC Voltage
FL	50	Hz	Line Frequency
TC	2.69	ms	Diode Conduction Time
Z	0.46		Loss Allocation Factor
$\eta$	74.0	%	Efficiency Estimate
VMIN	83.0	V	Minimum DC Input Voltage
VMAX	374.8	V	Maximum DC Input Voltage

Input Section

Var	Value	Units	Description
RFUSE	10.00	$\Omega$	Fusible Resistor.
IAVG	0.06	A	Average Diode Bridge Current (DC Input Current)
MOV_VRATED	275	V	MOV Rated Voltage

Device Variables

Var	Value	Units	Description
Device	LNK623PG		PI Device Name
BVDSS	700		Drn-Src Bkdn Voltage
Device Mode	Default		Current Limit mode for device
PO	3.60	W	Total Output Power
VDRAIN Estimated	535.69	V	Actual Estimated Drain Voltage
VDS	11.89	V	On state Drain to Source Voltage
I2F_MIN	3.97	A <sup>2</sup> kHz	Minimum I2F
I2F_MAX	5.16	A <sup>2</sup> kHz	Maximum I2F
FS_AT_ILIMMIN	103316	Hz	Switching Frequency at Current Limit Minimum
KP	0.71		Continuous/Discontinuous Operating Ratio
KP_TRANSIENT	0.54		Transient Ripple to Peak Current Ratio
ILIMITMIN	0.20	A	Minimum Current Limit
ILIMITMAX	0.23	A	Maximum Current Limit
IRMS	0.09	A	Primary RMS Current (at VMIN)
DMAX	0.48		Maximum Duty Cycle
RTH_DEVICE	109.76	°C/W	PI Device Maximum Thermal Resistance
DEV_HSINK_TYPE	2 Oz (70 $\mu$ ) Copper PCB		PI Device Heatsink Type
DEV_HSINK_AREA	52	mm <sup>2</sup>	PI Device Heatsink Area

Clamp Circuit

Var	Value	Units	Description
Clamp Type	RCD Clamp		Clamp Circuit Type
VCLAMP	96	V	Estimated average clamping voltage
Estimated Clamp Loss	0.11	W	Clamp Dissipation

Feedback Winding

Var	Value	Units	Description
NFB	11		Feedback Winding Number of Turns
Layers	0.95		Feedback Winding Layers

Transformer Construction Parameters

Var	Value	Units	Description
Core Type	EEL16		Core Type
Core Material	NC-2H (Nicera) or Equivalent		Core Material
Bobbin Reference	Generic, 4 pri. + 6 sec.		Bobbin Reference
Bobbin Orientation	Vertical		Bobbin type
Primary Pins	4		Number of Primary pins used
Secondary Pins	5		Number of Secondary pins used
USE_SHIELDS	YES		Use shield Windings
LP_nom	2557	μH	Nominal Primary Inductance
LP_Tol	10.0	%	Primary Inductance Tolerance
NP	113.0		Calculated Primary Winding Total Number of Turns
NSM	10		Secondary Main Number of Turns
CMA	430	Cmils/A	Primary Winding Current Capacity
VOR	64.4	V	Reflected Output Voltage
BW	17.60	mm	Bobbin Winding Width
ML	3.20	mm	Safety Margin on Left Width
MR	3.20	mm	Safety Margin on Right Width
FF	62	%	Actual Transformer Fit Factor. 100% signifies fully utilized winding window
AE	19.40	mm²	Core Cross Sectional Area
ALG	180	nH/T²	Gapped Core Effective Inductance
BM	2429	Gauss	Maximum Flux Density
BAC	749	Gauss	AC Flux Density for Core Loss
LG	0.107	mm	Estimated Gap Length
L_LKG	102.28	μH	Estimated primary leakage inductance
LSEC	15	nH	Secondary Trace Inductance

Primary Winding Section 1

Var	Value	Units	Description
NP1	114		Rounded (Integer) Number of Primary winding turns in the first section of primary
Wire Size	34	AWG	Wire size of primary winding
Winding Type	Single (x1)		Primary winding number of parallel wire strands
L	1.94		Primary Number of Layers
DC Copper Loss	0.03	W	Primary 1 DC Losses

Output 1

Var	Value	Units	Description
VO	18.00	V	Output Voltage
IO	0.15	A	Output Current
VOUT_ACTUAL	18.08	V	Actual Output Voltage
NS	24		Secondary Number of Turns
Wire Size	33	AWG	Wire size of secondary winding
Winding Type	Single (x1)		Output winding number of parallel strands
L_S_OUT	0.46		Secondary Output Winding Layers
DC Copper Loss	0.03	W	Secondary DC Losses
VD	1.30	V	Output Winding Diode Forward Voltage Drop

PIVS	130	V	Output Rectifier Maximum Peak Inverse Voltage
ISP	0.46	A	Peak Secondary Current
ISRMS	0.23	A	Secondary RMS Current
RTH_DIODE	196.44	°C/W	Output Diode Maximum Thermal Resistance
OD_HSINK_TYPE	2 Oz (70 µ) Copper PCB		Output Diode Heatsink Type
OD_HSINK_AREA	52	mm²	Output Diode Heatsink Area
CO	47 x 1	µF	Output Capacitor
IRIPPLE	0.17	A	Output Capacitor RMS Ripple Current
Expected Lifetime	23281	hr	Expected Lifetime of Output Capacitor

## Output 2

Var	Value	Units	Description
VO	5.00	V	Output Voltage
IO	0.15	A	Output Current
VOUT_ACTUAL	5.00	V	Actual Output Voltage.
NS	10		Secondary Number of Turns
Wire Size	30	AWG	Wire size of secondary winding
Winding Type	Single (x1)		Output winding number of parallel strands
L_S_OUT	0.26		Secondary Output Winding Layers
DC Copper Loss	0.03	W	Secondary DC Losses
VD	0.70	V	Output Winding Diode Forward Voltage Drop
PIVS	38	V	Output Rectifier Maximum Peak Inverse Voltage
ISP	0.46	A	Peak Secondary Current
ISRMS	0.23	A	Secondary RMS Current
RTH_DIODE	395.90	°C/W	Output Diode Maximum Thermal Resistance
OD_HSINK_TYPE	2 Oz (70 µ) Copper PCB		Output Diode Heatsink Type
OD_HSINK_AREA	52	mm²	Output Diode Heatsink Area
CO	100 x 1	µF	Output Capacitor
IRIPPLE	0.17	A	Output Capacitor RMS Ripple Current
Expected Lifetime	23281	hr	Expected Lifetime of Output Capacitor

## Output 3

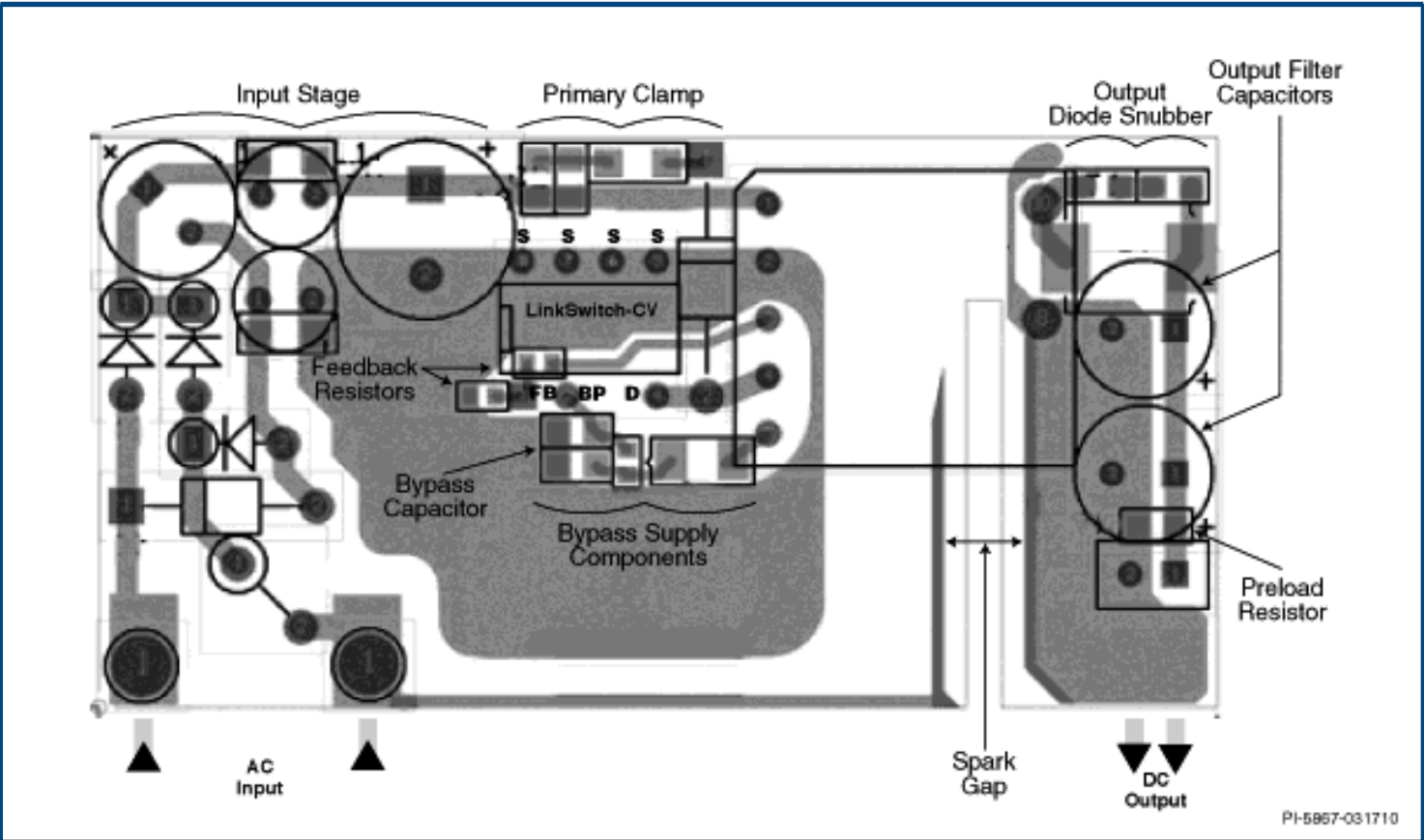
Var	Value	Units	Description
VO	5.00	V	Output Voltage
IO	0.03	A	Output Current
VOUT_ACTUAL	5.00	V	Actual Output Voltage
NS	10		Secondary Number of Turns
Wire Size	38	AWG	Wire size of secondary winding
Winding Type	Single (x1)		Output winding number of parallel strands
L_S_OUT	0.11		Secondary Output Winding Layers
DC Copper Loss	0.00	W	Secondary DC Losses
VD	0.70	V	Output Winding Diode Forward Voltage Drop
PIVS	38	V	Output Rectifier Maximum Peak Inverse Voltage
ISP	0.09	A	Peak Secondary Current
ISRMS	0.05	A	Secondary RMS Current
RTH_DIODE	2134.55	°C/W	Output Diode Maximum Thermal Resistance
OD_HSINK_TYPE	2 Oz (70 µ) Copper PCB		Output Diode Heatsink Type

OD_HSINK_AREA	<b>52</b>	mm <sup>2</sup>	Output Diode Heatsink Area
CO	<b>100 x 1</b>	μF	Output Capacitor
IRIPPLE	<b>0.03</b>	A	Output Capacitor RMS Ripple Current
Expected Lifetime	<b>31595</b>	hr	Expected Lifetime of Output Capacitor

The regulation and tolerances do not account for thermal drifting and component tolerance of the output diode forward voltage drop and voltage drops across the LC post filter. The actual voltage values are estimated at full load only.

Please verify cross regulation performance on the bench.

Board Layout Recommendations



PI-5857-031710

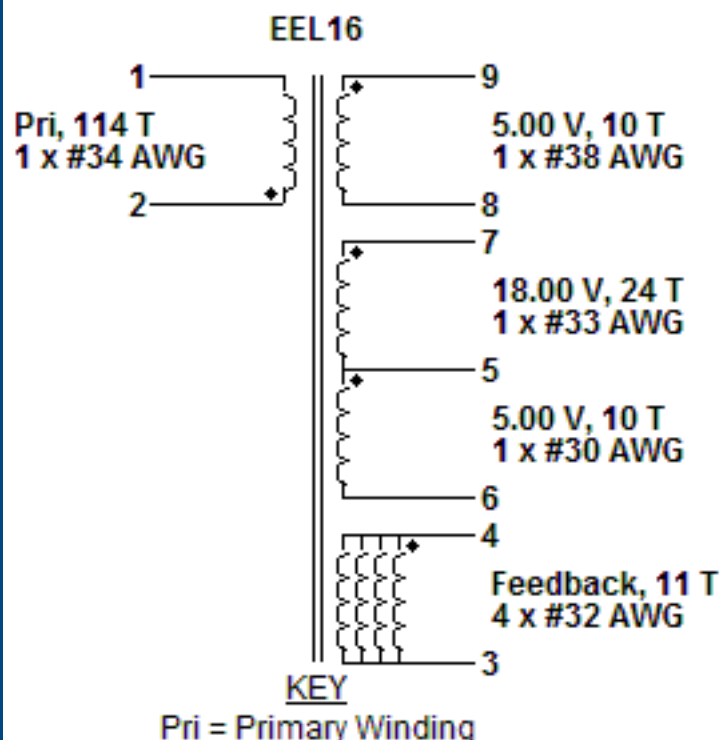
Click on the "Show me" icon to highlight relevant areas on the sample layout.

	Description	Show Me
1	Maximize source area for good heat-sinking	
2	Keep drain trace short	
3	The BYPASS pin capacitor should be located as close as possible to the BYPASS and SOURCE pins	
4	Keep noisy traces away from FB pin	
5	Route bias winding currents directly back to the bulk cap via a dedicated trace	
6	Keep clamp loop short	
7	The Y capacitor should be placed directly from the primary input filter capacitor positive terminal to the common/return terminal of the transformer secondary	
8	The area of the loop connecting the secondary winding, the output diode and the output filter capacitor should be minimized	

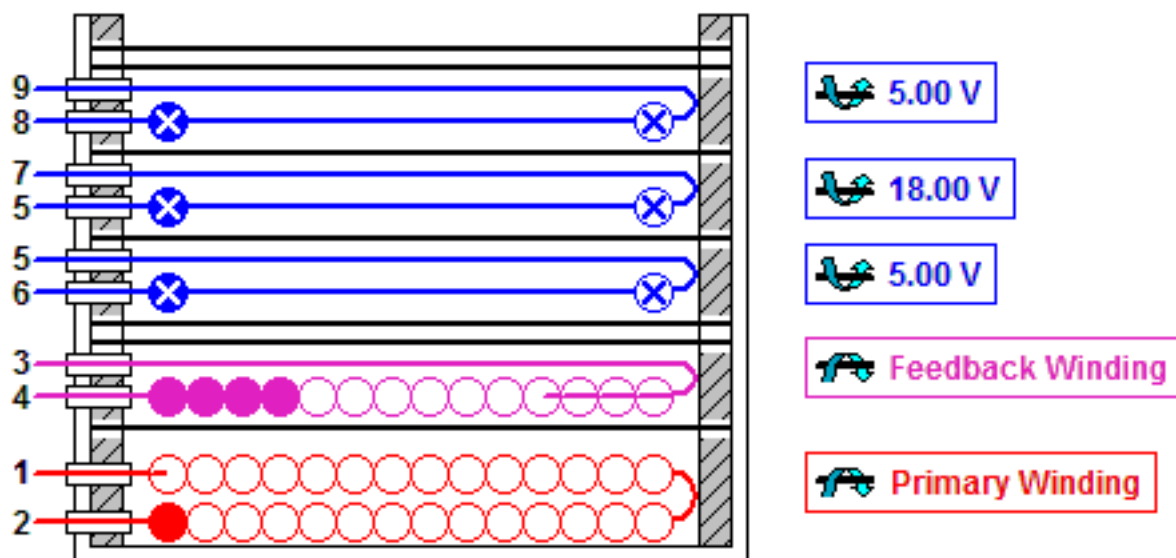
**Bill Of Materials**

<i><b>Ite m #</b></i>	<i><b>Quantity</b></i>	<i><b>Part Ref</b></i>	<i><b>Value</b></i>	<i><b>Description</b></i>	<i><b>Mfg</b></i>	<i><b>Mfg Part Number</b></i>
1	2	C1, C2	4.7 $\mu$ F	4.7 $\mu$ F, 400 V, High Voltage Al Electrolytic, (16 mm x 10 mm)	Nippon Chemi-Con	ESMG401ELL4R7MJ16S
2	1	C3	0.56 nF	0.56 nF, 1 kV, High Voltage Ceramic	Panasonic	ECK-D3A561KBN
3	1	C4	1 $\mu$ F	1 $\mu$ F, 16 V, Ceramic, X7R	TDK	C1608X7R1C105K
4	1	C5	2.2 nF	2.2 nF, 250 VAC, Ceramic, Y Class	TDK	CD12-E2GA222MYNS
5	2	C6, C8	470 pF	470 pF, 50 V, Ceramic, C0G	TDK	FK18C0G1H471J
6	1	C7	22 pF	22 pF, 1 kV, High Voltage Ceramic	Panasonic	ECC-D3A220JGE
7	2	C9, C11	100 $\mu$ F	100 $\mu$ F, 10 V, Electrolytic, Super Low ESR, 300 m $\Omega$ , (11 mm x 5 mm)	United Chemi-Con	EKZE100ELL101ME11D
8	1	C10	47 $\mu$ F	47 $\mu$ F, 25 V, Electrolytic, Super Low ESR, 300 m $\Omega$ , (11 mm x 5 mm)	United Chemi-Con	EKZE250ELL470ME11D
9	4	D1, D2, D3, D4	1N4006	800 V, 1 A, Standard Recovery, DO-41	Vishay	1N4006
10	1	D5	1N4937	600 V, 1 A, Fast Recovery, 200 ns, DO-41	Vishay	1N4937
11	2	D6, D8	SB150	50 V, 1 A, Schottky, DO-41	Vishay	SB150
12	1	D7	BYV26B	400 V, 1 A, Ultrafast Recovery, 30 ns, SOD57	Philips	BYV26B
13	2	L1, L2	1 mH	1 mH, 0.19 A	TDK	TSL0709RA-102KR19-PF
14	1	R1	270 k $\Omega$	270 k $\Omega$ , 5 %, 0.25 W, Carbon Film	Generic	
15	1	R2	43 $\Omega$	43 $\Omega$ , 5 %, 0.25 W, Carbon Film	Generic	
16	2	R3, R5	22 $\Omega$	22 $\Omega$ , 5 %, 0.25 W, Carbon Film	Generic	
17	1	R4	470 $\Omega$	470 $\Omega$ , 5 %, 0.25 W, Carbon Film	Generic	
18	1	R6	16.2 k $\Omega$	16.2 k $\Omega$ , 1 %, 0.125 W, Metal Film	Generic	
19	1	R7	6.65 k $\Omega$	6.65 k $\Omega$ , 1 %, 0.125 W, Metal Film	Generic	
20	1	RF1	10 $\Omega$	10 $\Omega$ , 2 W, Flameproof Wire-Wound Resistor	Vitrohm	CRF253-4 10R
21	1	RV1	V275LA4P	275 V, 23 J, 7 mm, RADIAL, MOV	Littelfuse	V275LA4P
22	1	T1	EEL16	NC-2H (Nicer) or Equivalent Core Material See Transformer Construction's Materials List for complete information	TDK	PC40EE16/24/5-Z
23	1	U1	LNK623PG	LinkSwitch-CV, LNK623PG, DIP-8	Power Integrations	LNK623PG
24	1			52 mm <sup>2</sup> area on Copper PCB. 2 oz (70 $\mu$ m) thickness. Heatsink for use with Diode D6.	Custom	
25	1			52 mm <sup>2</sup> area on Copper PCB. 2 oz (70 $\mu$ m) thickness. Heatsink for use with Diode D7.	Custom	
26	1			52 mm <sup>2</sup> area on Copper PCB. 2 oz (70 $\mu$ m) thickness. Heatsink for use with Device U1.	Custom	
27	1			52 mm <sup>2</sup> area on Copper PCB. 2 oz (70 $\mu$ m) thickness. Heatsink for use with Diode D8.	Custom	

## Electrical Diagram



## Mechanical Diagram



### KEY

- Mechanical start of winding (also denotes electrical phase)
- ⊗ Mechanical start of reverse winding (connect to secondary RTN)
- ⊗ Positive polarity end of reverse winding (connect to secondary diode)
- ↻ Direction of winding (clockwise)
- ↻ Direction of reverse winding (anti-clockwise)

## Winding Instruction

Use 3.20 mm margin (item [3]) on the bottom. Use 3.20 mm margin (item [3]) on the top.



Primary Winding

Start on pin(s) 2 using item [5] at the start leads and wind 114 turns (x 1 filar) of item [7]. in 2 layer(s) from left to right. At the end of 1st layer, continue to wind the next layer from right to left. On the final layer, spread the winding evenly across entire bobbin. Finish this winding on pin(s) 1 using item [5] at the finish leads.

Add 1 layer of tape, item [4], for insulation.

Feedback Winding

Start on pin(s) 4 using item [5] at the start leads and wind 11 turns (x 4 filar) of item [8]. Wind in same rotational direction as primary winding. Spread the winding evenly across entire bobbin. Finish this winding on pin(s) 3 using item [5] at the finish leads.

Add 2 layers of tape, item [4], for insulation.

Secondary Winding

Start on pin(s) 6 using item [5] at the start leads and reverse wind 10 turns (x 1 filar) of item [9]. Spread the winding evenly across entire bobbin. Wind in opposite rotational direction as primary winding. Finish this winding on pin(s) 5 using item [5] at the finish leads.

Add 1 layer of tape, item [4], for insulation.

Start on pin(s) 5 using item [5] at the start leads and reverse wind 24 turns (x 1 filar) of item [10]. Spread the winding evenly across entire bobbin. Wind in opposite rotational direction as primary winding. Finish this winding on pin(s) 7 using item [5] at the finish leads.

Add 1 layer of tape, item [4], for insulation.

Start on pin(s) 8 using item [5] at the start leads and reverse wind 10 turns (x 1 filar) of item [11]. Spread the winding evenly across entire bobbin. Wind in opposite rotational direction as primary winding. Finish this winding on pin(s) 9 using item [5] at the finish leads.

Add 2 layers of tape, item [4], for insulation.

Core Assembly

Assemble and secure core halves. Item [1].

Varnish

Dip varnish uniformly in item [6]. Do not vacuum impregnate.

Materials

Item	Description
[1]	Core: EEL16, NC-2H (Nicera) or Equivalent, gapped for ALG of 180 nH/T²
[2]	Bobbin: Generic, 4 pri. + 6 sec.
[3]	Tape: Polyester web 3.20 mm wide
[4]	Barrier Tape: Polyester film [1 mil (25 µm) base thickness], 17.60 mm wide
[5]	Teflon Tubing # 22
[6]	Varnish
[7]	Magnet Wire: 34 AWG, Solderable Double Coated
[8]	Magnet Wire: 32 AWG, Solderable Double Coated
[9]	Magnet Wire: 30 AWG, Solderable Double Coated
[10]	Magnet Wire: 33 AWG, Solderable Double Coated
[11]	Magnet Wire: 38 AWG, Solderable Double Coated

Electrical Test Specifications

Parameter	Condition	Spec
Electrical Strength, VAC	60 Hz 1 second, from pins 1,2,3,4 to pins 5,6,7,8,9.	4000
Nominal Primary Inductance, µH	Measured at 1 V pk-pk, typical switching frequency, between pin 1 to pin 2, with all other Windings open.	2557
Tolerance, ±%	Tolerance of Primary Inductance	10.0
Maximum Primary Leakage, µH	Measured between Pin 1 to Pin 2, with all other Windings shorted.	102.28

Although the design of the software considered safety guidelines, it is the user's responsibility to ensure that the user's power supply design meets all applicable safety requirements of user's product.

	<b>Description</b>	<b>Fix</b>	<b>Ref. #</b>
	Some of the specified tolerances could not be met (Tolerance better than 10%). See design results for details.	Reassign another output as main output and try to reoptimize the design. Enable DC stacking from preferences and try reoptimizing design or Increase tolerance.	149
	Fusible Resistor is used.	Make sure to use a wire-wound, flameproof, fusible resistor for RF1.	165